



**Advanced Power
Electronics Corp.**

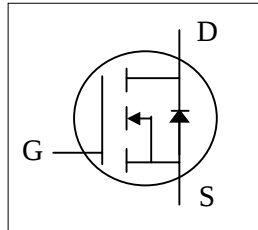
AP60L02GH/J

Pb Free Plating Product

N-CHANNEL ENHANCEMENT MODE

POWER MOSFET

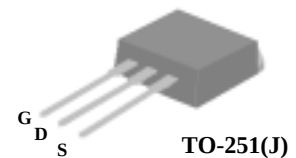
- ▼ Low Gate Charge
- ▼ Simple Drive Requirement
- ▼ Fast Switching



BV_{DSS}	25V
$R_{DS(ON)}$	12m Ω
I_D	50A

Description

The TO-252 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP60L02GJ) is available for low-profile applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	25	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	50	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	32	A
I_{DM}	Pulsed Drain Current ¹	180	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	62.5	W
	Linear Derating Factor	0.5	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-case	Thermal Resistance Junction-case Max.	2.0	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal Resistance Junction-ambient Max.	110	$^\circ\text{C}/\text{W}$



AP60L02GH/J

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	25	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.037	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =25A	-	-	12	mΩ
		V _{GS} =4.5V, I _D =20A	-	-	26	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =25A	-	30	-	S
I _{DSS}	Drain-Source Leakage Current (T _j =25°C)	V _{DS} =25V, V _{GS} =0V	-	-	1	uA
	Drain-Source Leakage Current (T _j =150°C)	V _{DS} =20V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V		-	±100	nA
Q _g	Total Gate Charge ²	I _D =25A	-	21		nC
Q _{gs}	Gate-Source Charge	V _{DS} =20V	-	2.8		nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =5V	-	16		nC
t _{d(on)}	Turn-on Delay Time ²	V _{DS} =15V	-	8	-	ns
t _r	Rise Time	I _D =20A	-	75	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω, V _{GS} =10V	-	22	-	ns
t _f	Fall Time	R _D =0.75Ω	-2	0	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	605	-	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	415	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	195	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I _S	Continuous Source Current (Body Diode)	V _D =V _G =0V , V _S =1.26V	-	-	50	A
I _{SM}	Pulsed Source Current (Body Diode) ¹		-	-	180	A
V _{SD}	Forward On Voltage ²	T _j =25°C, I _S =50A, V _{GS} =0V	-	-	1.26	V

Drain-Source Avalanche Ratings

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
E _{AS}	Single Pulse Avalanche Energy ²	V _{DD} =25V, I _D =35A, L=100uH	-	-	61	mJ
I _{AR}	Avalanche Current	V _{GS} =10V	-	-	35	A

Notes:

- 1.Pulse width limited by safe operating area.
- 2.Pulse width ≤300us , duty cycle ≤2%.

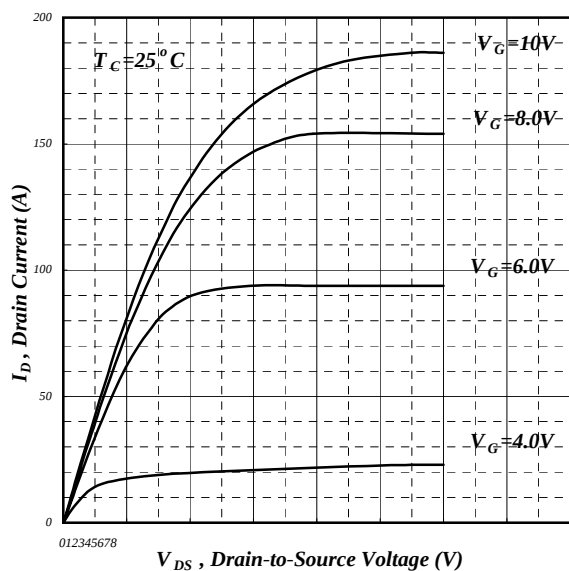


Fig 1. Typical Output Characteristics

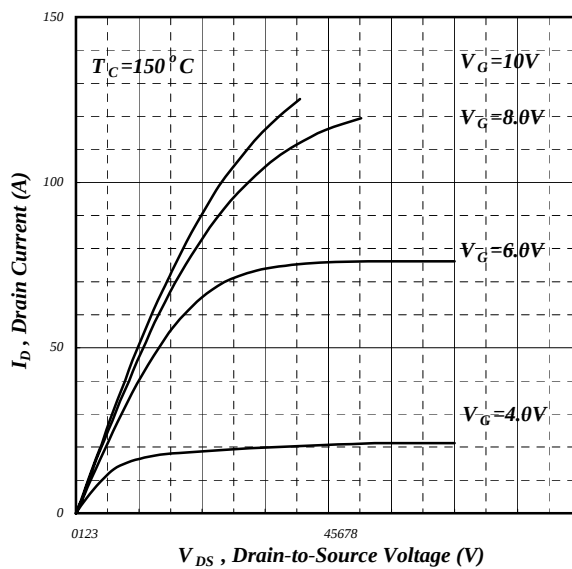


Fig 2. Typical Output Characteristics

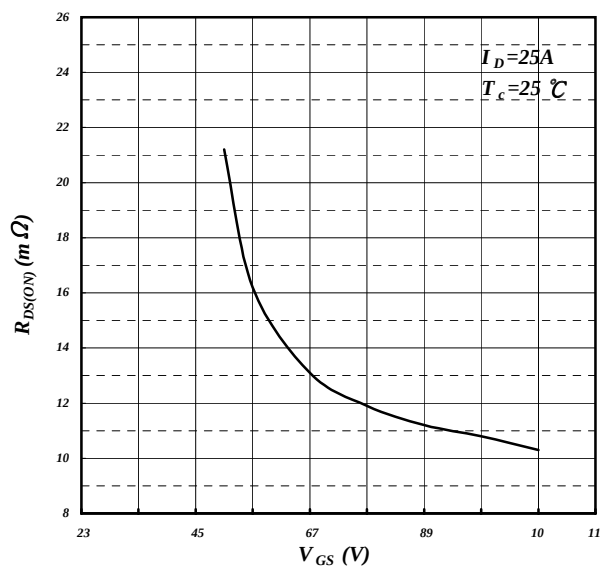


Fig 3. On-Resistance v.s. Gate Voltage

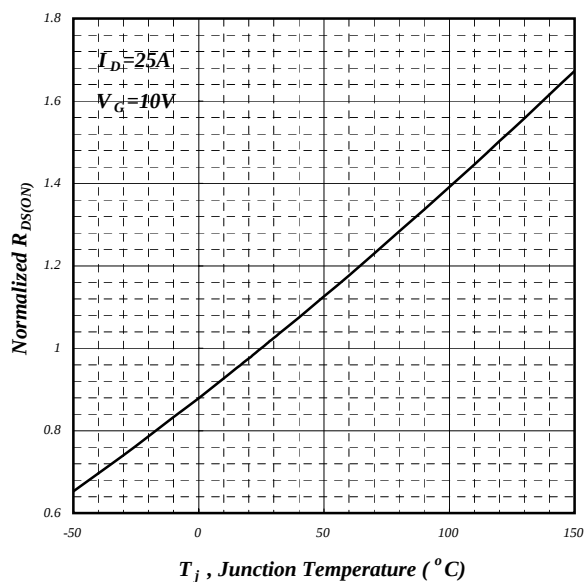


Fig 4. Normalized On-Resistance v.s. Junction Temperature



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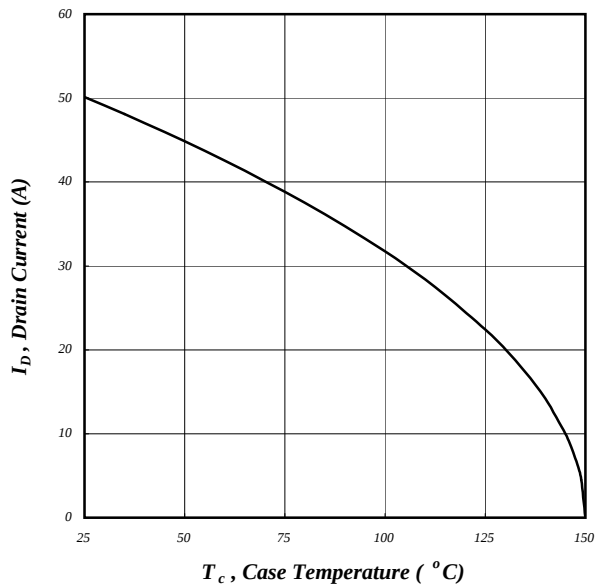


Fig 5. Maximum Drain Current v.s. Case Temperature

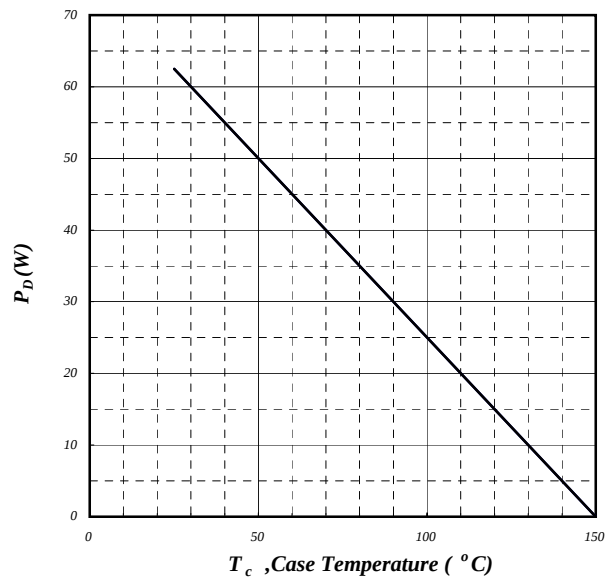


Fig 6. Typical Power Dissipation

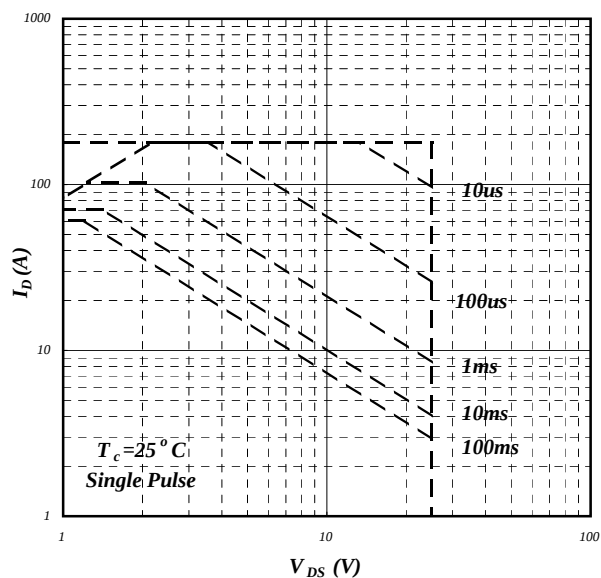


Fig 7. Maximum Safe Operating Area

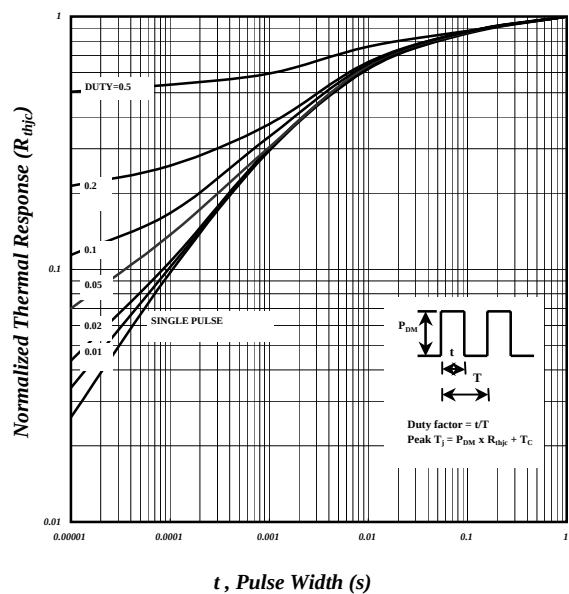
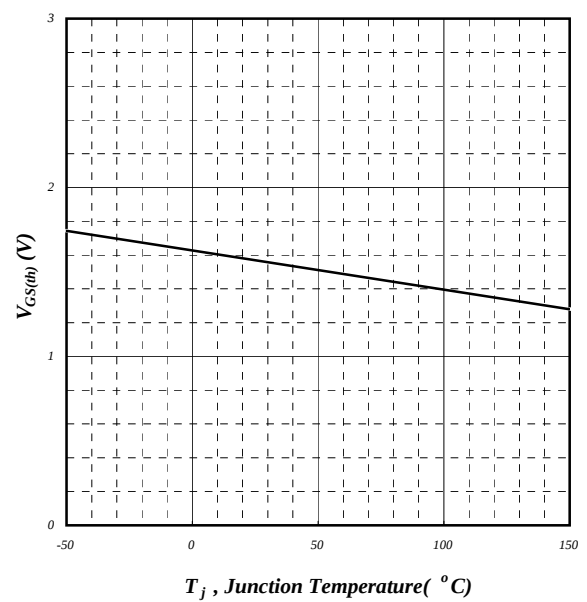
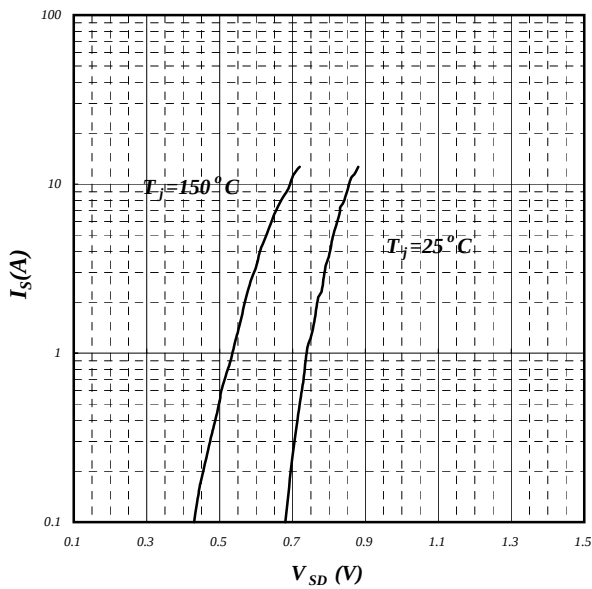
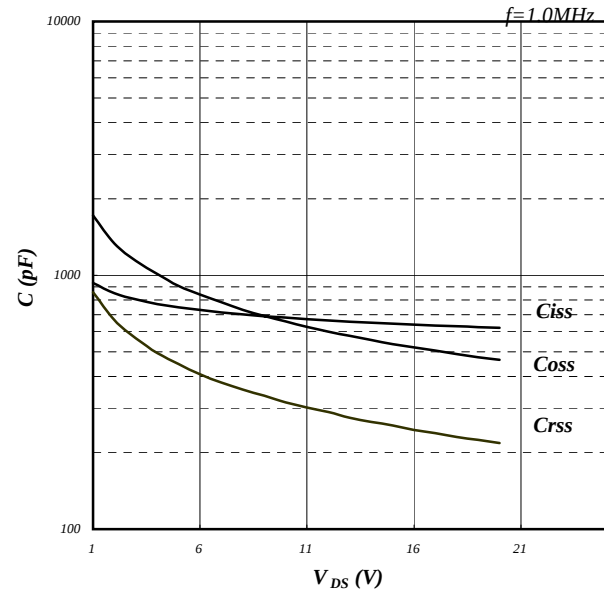
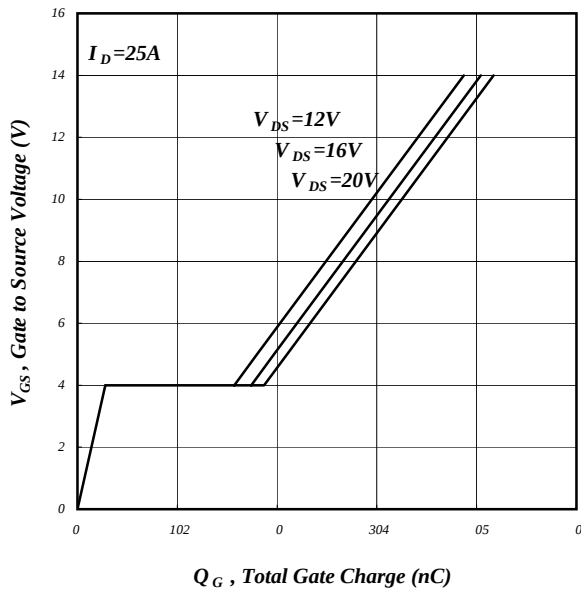


Fig 8. Effective Transient Thermal Impedance



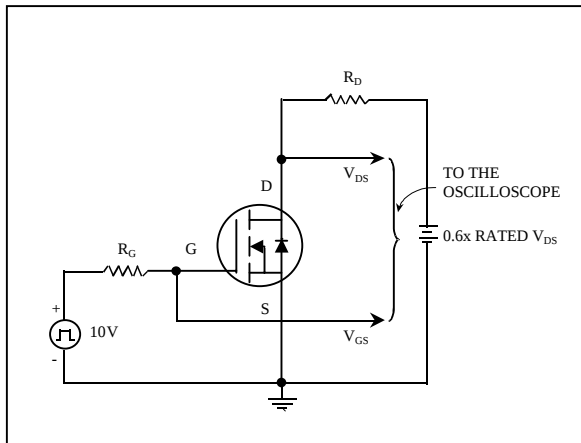


Fig 13. Switching Time Circuit

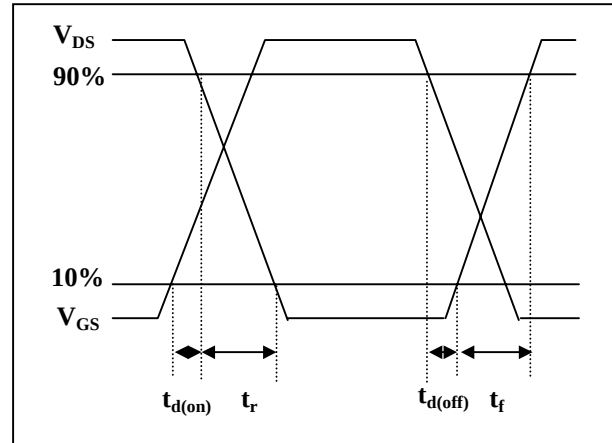


Fig 14. Switching Time Waveform

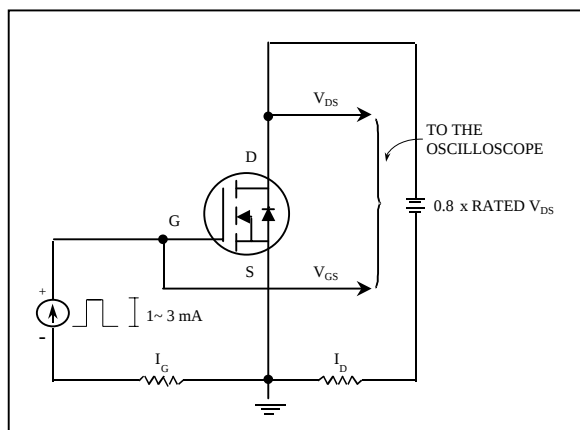


Fig 15. Gate Charge Circuit

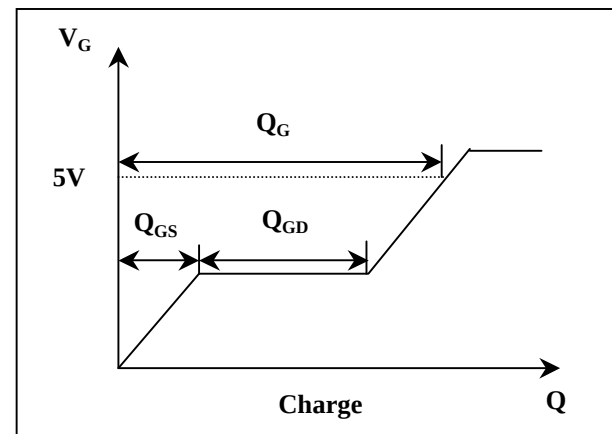


Fig 16. Gate Charge Waveform